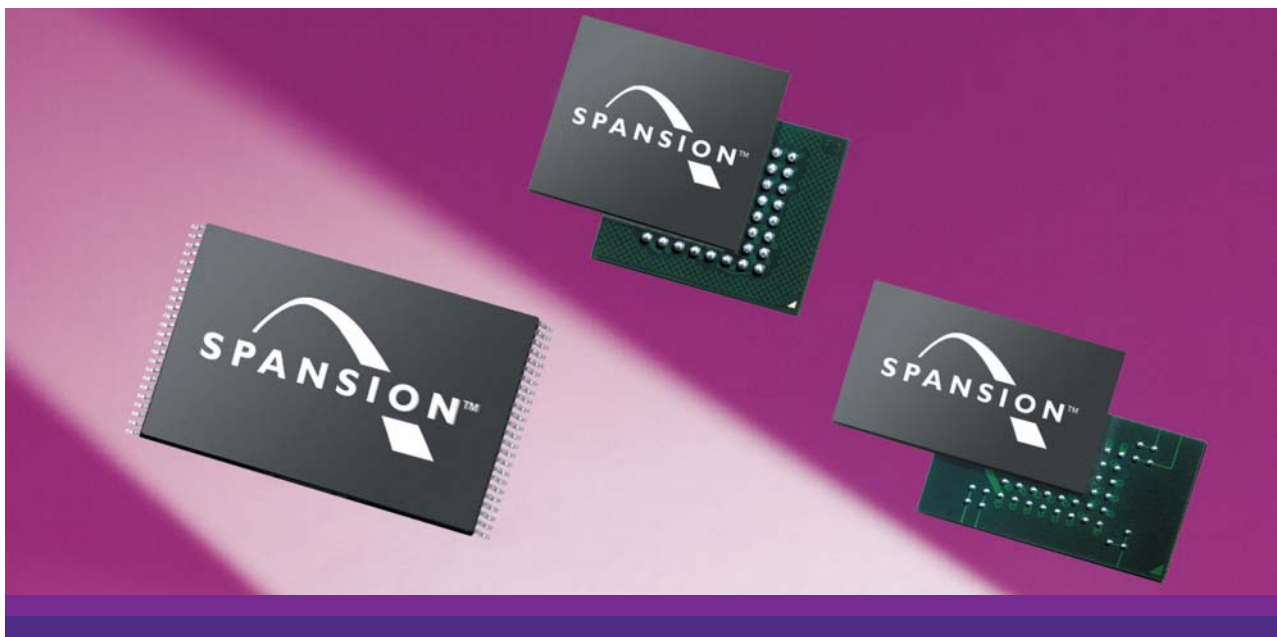




THE WORLD'S LEADING SUPPLIER  
OF NOR FLASH MEMORY



June 2004 Edition



As the world's leading supplier of NOR Flash memory solutions, we don't take our success for granted. We understand that enabling our customers' success, whether in wireless or embedded markets, is critical to our success. That's why we strive to delight our customers with the perfect memory solution – time after time.

Spansion is based on a longstanding partnership between AMD and Fujitsu that began operations in 1993. Fueled by breakthrough innovation, world-class manufacturing, and a stellar global team, our partnership and joint venture propelled AMD and Fujitsu to enduring positions of leadership in the Flash memory marketplace.

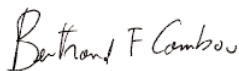
We are proud that our partnership became one of the most successful joint ventures in the history of US-Japan collaboration. As a result, we decided to raise our partnership to the next level of teamwork, excellence, and leadership.

In 2003, AMD and Fujitsu created Spansion: a unified, new company dedicated to becoming the world's leading supplier of non-volatile memory solutions. With assets of approximately \$3 billion and a global team of approximately 7000 employees, Spansion is the largest company in the world focused exclusively on the development and manufacturing of Flash memory.

As AMD and Fujitsu bring Spansion™ Flash memory products – many featuring award-winning MirrorBit™ technology – to the global marketplace, they will continue a legacy of award-winning service and support. Together Spansion, AMD, and Fujitsu are working harder, smarter, and faster to enable our customers' success with innovative Flash memory solutions.

We look forward to sharing that experience with you the customer, our most valuable asset, for a long time to come.

Best regards,



Bertrand Cambou  
President and CEO  
Spansion



## MARKET LEADERSHIP

Spansion is founded on the powerful idea that leadership enables breakaway customer success. Our leadership begins with a deep understanding of a customer's most difficult challenges. And our leadership is demonstrated by the ability to consistently deliver solutions that meet those challenges.

### Flash Memory Leadership for Wireless Markets

The Spansion Flash memory portfolio accelerates the incredible pace of innovation in wireless design by combining rapid innovation with leading-edge technology. Engineered using advanced silicon and packaging technologies, Spansion Flash memory for wireless delivers the features critical for creating breakthrough mobile applications with smaller form factors, longer system battery life, and compelling price-performance.

### Flash Memory Leadership for Embedded Markets

From automotive to networking to consumer electronics and beyond, designers of embedded applications require memory solutions as diverse as their designs. That's why the Spansion memory portfolio delivers the industry's broadest selection of Flash memory devices, to enable innovation across a wide range of embedded applications. That's also why Spansion Flash memory products are engineered for superb reliability, extraordinary quality, and extended product longevity to enable innovation in extreme operating conditions.



#### *Features for Wireless Markets:*

- Advanced Multi-Chip Products (MCP)
- High-performance Burst mode and Page mode
- Robust security with Advanced Sector Protection
- Ultra-low energy consumption

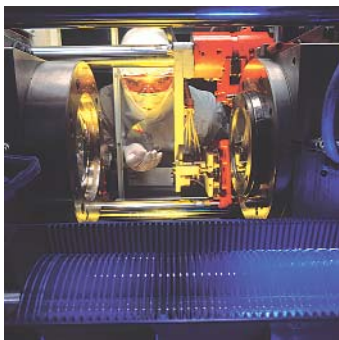


#### *Features for Embedded Markets:*

- An industry leading cost structure featuring MirrorBit™ technology
- Broad product portfolio from 1 to 512 Mb
- JEDEC-standard hardware and software for easy migration and design reuse
- Robust security with Advanced Sector Protection

## TECHNOLOGY LEADERSHIP

Since 1993, the partnership between AMD and Fujitsu has established an enduring legacy of technology leadership. From the world's first single-power Flash memory device to the groundbreaking MirrorBit technology, our innovations have been a driving force behind the industry's development and our customers' success.



By combining the intellectual property and technical expertise of its rich history, Spansion carries the torch of technology leadership. And with more than 700 technology, design, and production engineers completely focused on memory innovation, we are well positioned to extend our leadership in the years to come.

### Spansion Memory Technology At-A-Glance

- Over 700 technology, design, and production engineers focused entirely on memory technology
- Submicron Development Center (Sunnyvale, CA) - 42,000 square foot fabrication facility dedicated to advanced research & development in silicon and process technology
- MCP Development Center (Suzhou, China) - Center of excellence developing next-generation packaging technology
- Access to AMD's and Fujitsu's leading edge memory technology patents
- QS-9000 Certified Quality Systems (TS16949 certification underway)

1992

World's first single power-supply  
Flash memory device

1992

Negative Gate Erase Technology

1996

Industry's first 2.7V and  
1.8V single power-supply  
Flash memory devices

1997

Simultaneous Read/Write  
(EDN Innovation of the Year)

1997

Industry's first  
Known Good Die  
Flash memory

1998

First Page mode Flash memory  
device

1999

First Burst mode Flash memory  
device

2000

First Multi-Chip Product with  
Flash + SRAM in a single package

2001

Industry's first Flash memory  
device featuring a 32-bit databus

2002

MirrorBit™ technology  
introduced

2002

Advanced Sector Protection  
introduced

2003

Industry's first 512Mb  
NOR Flash memory  
(Second-generation  
MirrorBit technology)

2004

1.8 volt, 80MHz Burst mode  
Flash memory introduced  
(Second-generation  
MirrorBit technology)

## GLOBAL LEADERSHIP

Global leadership requires more than an international presence. It combines regional focus with global perspective, insight, and vision. It unites a widely distributed team through commonly held values and clear communications. And it delivers memory solutions and business value to perfectly satisfy a global network of customers.

Built upon one of the most successful joint ventures in the history of US-Japan collaboration, Spansion leverages a unique, finely tuned model of global leadership. With over ten years of partnership and a highly successful company integration under way, we have established industry-leading practices in cross-cultural communication and global teamwork. Combined with a keen understanding of regional markets and a single-minded drive toward excellence, Spansion sets the bar for global leadership in non-volatile memory.

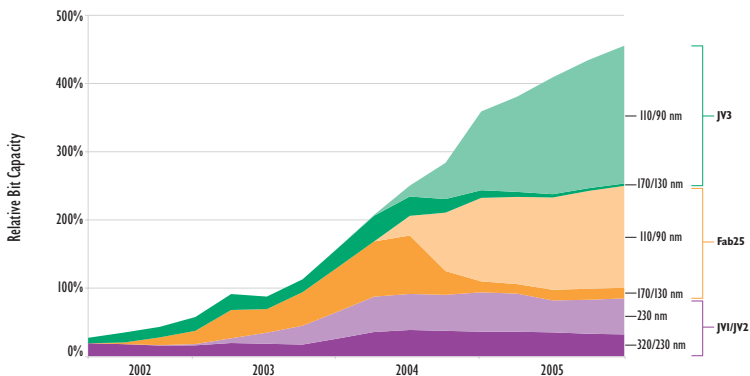
Rank	Supplier	Market Share
1	<b>Spansion</b>	<b>27.8%</b>
2	Intel	18.3%
3	ST Microelectronics	12.2%
4	Sharp Electronics	11.7%
5	Toshiba	5.5%
6	Renesas Technology	5.1%
7	Silicon Storage Technology	4.6%
8	Macronix International	3.5%
9	Samsung	2.9%
—	All others combined	8.3%

Source: iSuppli Market Analysis (May 2004)

## AWARD-WINNING SALES AND SUPPORT FROM AMD AND FUJITSU

As the global suppliers of Spansion memory solutions, AMD and Fujitsu are committed to delivering outstanding customer service and expert technical support. To learn more about Spansion Flash memory solutions, contact your local sales representative or visit [www.spansion.com](http://www.spansion.com).

## MEGAFAB PRODUCT RAMP – SPANSION™ FLASH MEMORY



Source: Spansion estimates, May 2004

## AMD and Fujitsu: Traditions of Customer Service and Industry Distinction



CISCO SYSTEMS  
SUPPLIER OF  
THE YEAR



CISCO SYSTEMS  
PRESIDENT'S  
CUSTOMER  
SATISFACTION



VOLKSWAGEN  
LEADING EDGE  
CORPORATE  
SUPPLIER OF  
THE YEAR



NORTEL  
NETWORKS  
SUPPLIER OF  
THE YEAR



EDN  
INNOVATOR  
OF THE YEAR



NORTEL  
NETWORKS  
SUPPLIER OF  
THE YEAR



BOSCH  
TOP MEMORY  
SUPPLIER



SAMSUNG  
BEST SUPPLIER



QS-9000  
CERTIFICATION

Global Team and  
Manufacturing  
Strength

Headquarters  
Sunnyvale, California

Headquarters  
Tokyo, Japan

Wafer fabrication facilities  
Aizu-Wakamatsu, Japan  
JVI, JV2, JV3 MegaFabs

Wafer fabrication facility  
Austin, Texas  
Fab 25 MegaFab

Wafer fabrication facility  
Sunnyvale, California  
Submicron Development  
Center

Final manufacturing facility  
Bangkok, Thailand

Final manufacturing facility  
Kuala Lumpur, Malaysia

Final manufacturing facility  
Penang, Malaysia

Final manufacturing facility  
Suzhou, China

## ABOUT SPANSION™ FLASH MEMORY PRODUCTS

Spansion™ Flash memory products encompass a broad spectrum of densities and features to support a wide range of markets. Spansion Flash memory customers represent leaders in the wireless, cellular, automotive, networking, telecommunications and consumer electronics markets. There is a variety of Spansion Flash memory products, such as devices based on the innovative MirrorBit™ technology; the award-winning simultaneous read-write (SRW) product family; super low-voltage 1.8 volt Flash memory devices; and burst- and page-mode devices. Information about Spansion Flash memory solutions is available at <http://www.spansion.com/overview>.

Spansion was formed by the integration of AMD's and Fujitsu's Flash memory operations in 2003. It is the largest NOR Flash memory company in the world. Spansion Flash memory solutions are available worldwide from AMD and Fujitsu.



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